

Appl. No. : 09/854,067
Filed : May 10, 2001

AMENDMENTS TO THE CLAIMS

Please amend the Claims as follows. Insertions are shown underlined while deletions are ~~struck through~~. Please cancel Claims 1 and 3-5.

1-6 (canceled)

7 (previously presented): A method of manufacturing an organic EL device comprising 1) a laminate consisting of an opposed pair of electrodes and an organic light-emitting layer sandwiched between the electrodes, 2) a gas-tight housing accommodating said laminate and shielding off the external atmosphere and 3) a desiccating means disposed in isolation from said laminate within said gas-tight housing, the method comprising:

forming a sheet-like preformed moisture-absorbing body comprising a desiccant and a resin component outside said gas-tight housing to prevent generation of impurities inside said gas-tight housing, which is generated during the formation of said preformed moisture-absorbing body; and

fixing said preformed moisture-absorbing body as desiccating means to at least one inner part of said gas-tight housing.

8 (previously presented): The manufacturing method according to Claim 7 wherein the forming of said preformed moisture-absorbing body comprises providing a mixture consisting of said desiccant and said resin component.

9 (currently amended): The method according to Claim 7 wherein said resin component is selected from ~~the~~a group consisting of polyolefins, polyacrylic acids or esters, polyacrylonitrile, polyamides, polyesters, epoxy resins and polycarbonates.

10 (currently amended): The method according to Claim 7 wherein said resin component is selected from ~~the~~a group consisting of polyethylene, polypropylene, polybutadiene and polyisoprene.

11 (previously presented): The method according to Claim 7 wherein the amount of said desiccant is about 30 to 85 weight % and that of said resin component is about 70 to 15 weight % based on 100 weight % of the desiccant and resin component combined.

12 (previously presented): The method according to Claim 7 wherein the amount of said desiccant is about 40 to 80 weight % and that of said resin component is about 60 to 20 weight % based on 100 weight % of the desiccant and resin component combined.

Appl. No. : **09/854,067**
Filed : **May 10, 2001**

13 (previously presented): The method according to Claim 7 wherein the amount of said desiccant is about 50 to 70 weight % and that of said resin component is about 50 to 30 weight % based on 100 weight % of the desiccant and resin component combined.

14 (previously presented): The method according to Claim 9 wherein said resin component is polyolefin.

15 (previously presented): The manufacturing method according to Claim 7 wherein the forming of said preformed moisture-absorbing body comprises integrating said desiccant and said resin component without using a solvent.

Appl. No. : 09/854,067
Filed : May 10, 2001


Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

KNOBBE MARTENS OLSON & BEAR LLP

Dated: June 16, 2004

By:



Katsuhiro Arai

Registration No. 43,315

Agent of Record

Customer No. 20,995

(949) 760-0404

H:\DOCS\TOS\SAEGU81.001AUS\SAEGU81.001AUS.AMEND5.DOC
061104